

Thermal Interface Material



S 900



- Pure graphite
- No binder

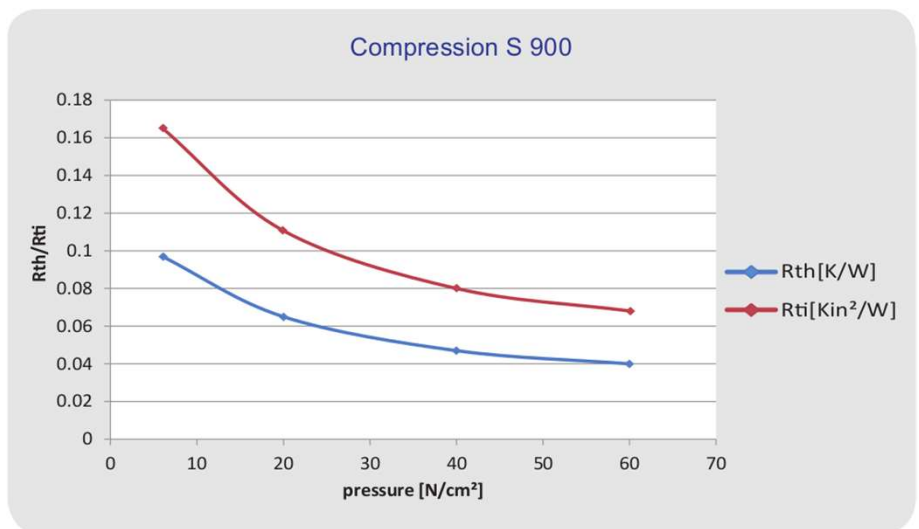
Applications

- Chipsets
- Memory chips
- Micro BGA

Options

- Available with standard adhesive as S 900K

Properties	Unit	S 900
Color		Gray
Thermal Properties		
Thermal Conductivity (XY)	W/mK	7.5 (>300)
Thermal Resistance	K/W	0.08
Electrical Properties		
Breakdown Voltage $U_{d;ac}$	kV	Conductive
Electrical Resistance (XY)	$\Omega\mu\text{m}$	700-800 (7-9)
Mechanical Properties		
Hardness	Shore D	25-35
Tensile Strength	N/mm ²	10
Elongation	%	5
Physical Properties		
Application Temperature	°C (°F)	-40 to +500 (-40 to +932)
Density	g/cm ³	>1.6
Total Mass Loss	Ma. %	0.01
Flame rating	UL-94	V-0
Possible Thickness	mm (inch)	0.15, 0.29 (0.006, 0.011)



The data provide engineering guidance, performance in actual applications should be established through testing.